

Thick Film Metallization: AgPd or AgPt

substrate material	ANCeram Aluminium Nitride (AlN)
surface	Standard, CLA < 1.0 µm
metallization	AgPd or AgPt paste
film thickness	14 µm (typ.), 10 µm (min.)
sheet resistivity	4.5 ± 0.5 mΩ/□
dimensions	according to customers' specification
min. line width	150 µm
min. line spacing	150 µm
recommended solder	Sn62PbAg2
adhesive strength	> 20 N/mm ²

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